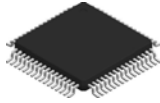


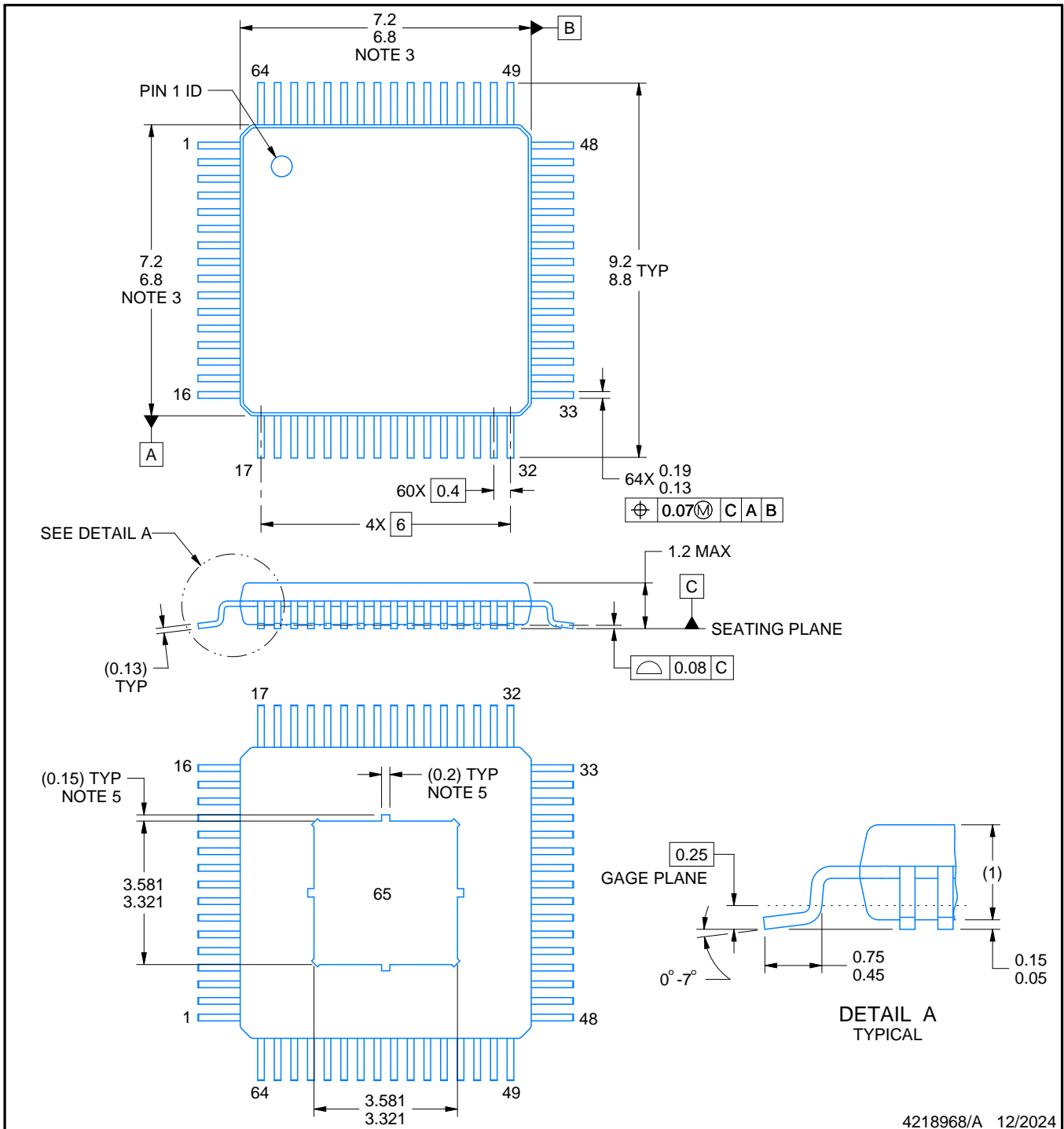
# PVP0064A



# PACKAGE OUTLINE

## PowerPAD™ HTQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



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### NOTES:

PowerPAD is a trademark of Texas Instruments.

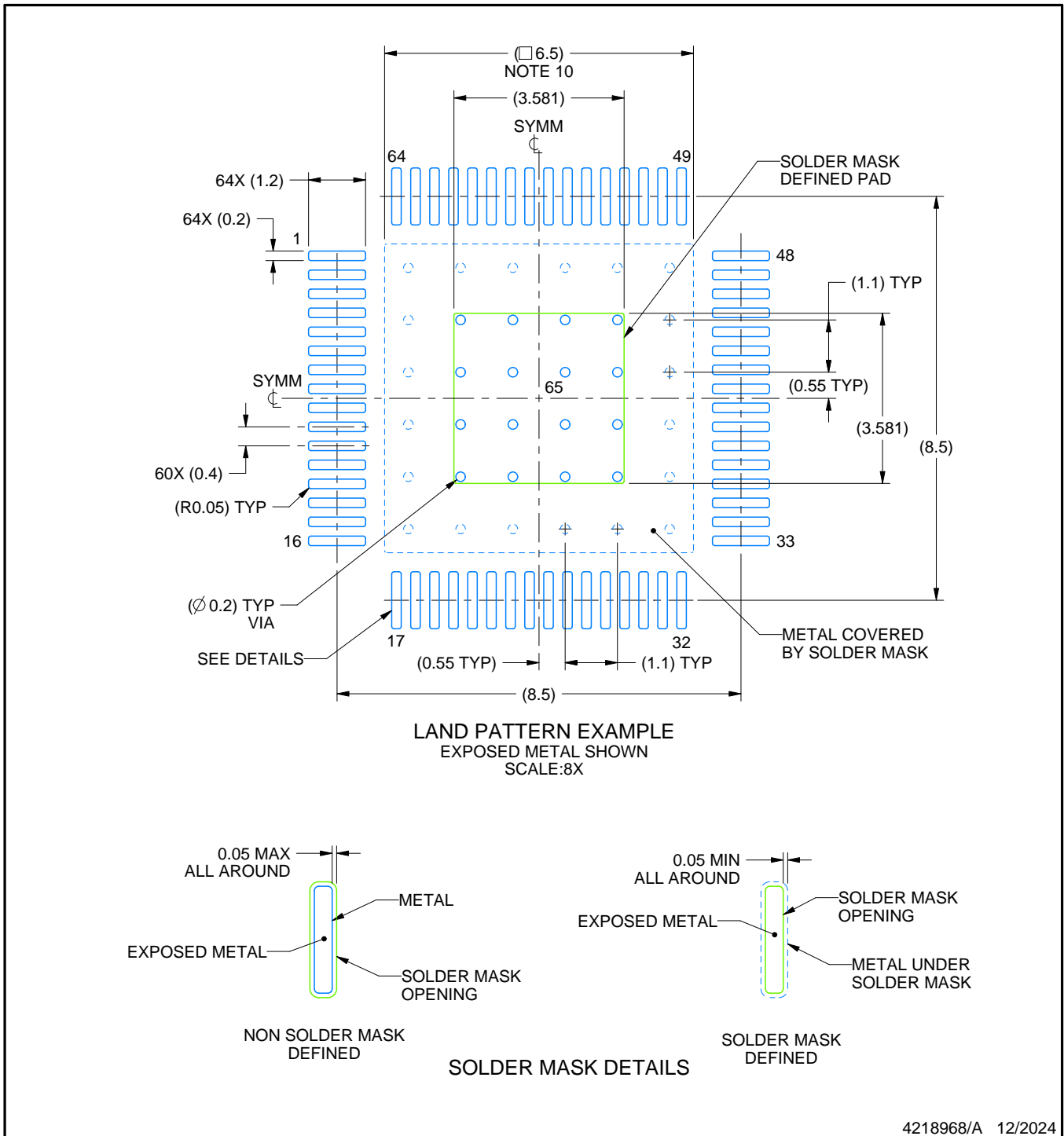
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MS-026.
5. Feature may not be present.

# EXAMPLE BOARD LAYOUT

PVP0064A

PowerPAD™ HTQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



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NOTES: (continued)

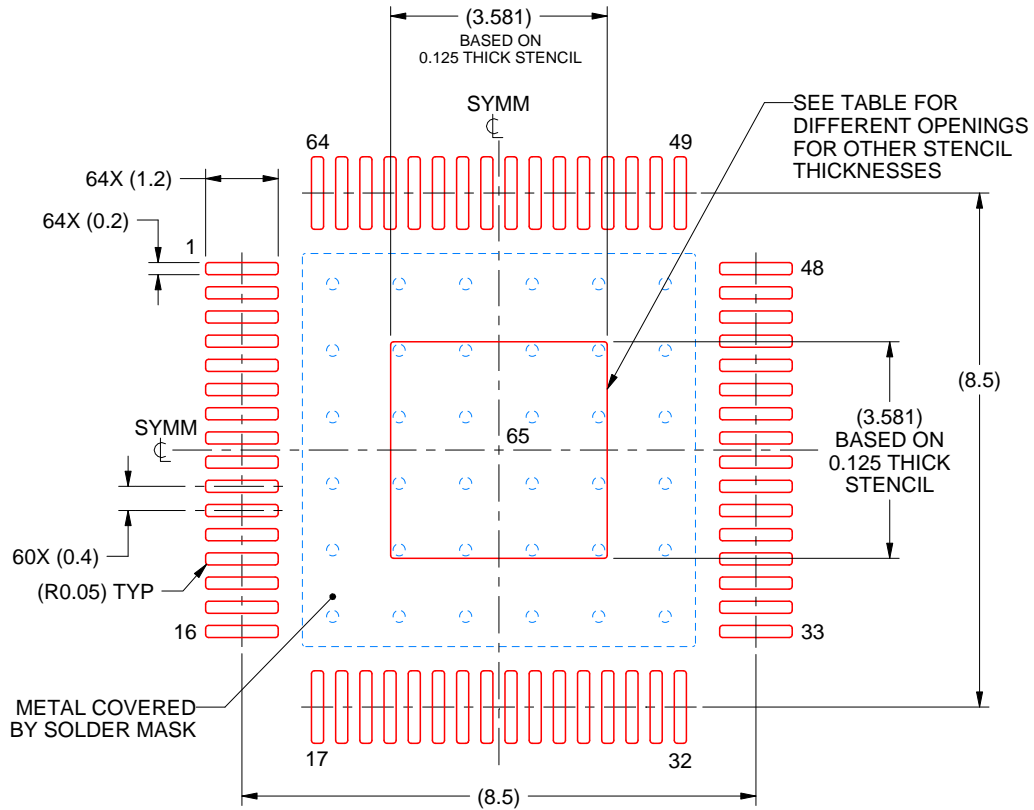
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. See technical brief, Powerpad thermally enhanced package, Texas Instruments Literature No. SLMA002 ([www.ti.com/lit/slma002](http://www.ti.com/lit/slma002)) and SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).
9. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.
10. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

PVP0064A

PowerPAD™ HTQFP - 1.2 mm max height

PLASTIC QUAD FLATPACK



SOLDER PASTE EXAMPLE  
 EXPOSED PAD  
 100% PRINTED SOLDER COVERAGE BY AREA  
 SCALE:8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	4.004 X 4.004
0.125	3.581 X 3.581 (SHOWN)
0.150	3.269 X 3.269
0.175	3.026 X 3.026

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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